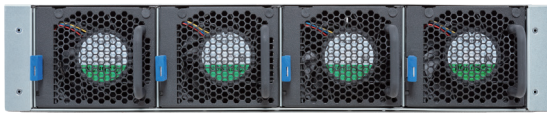
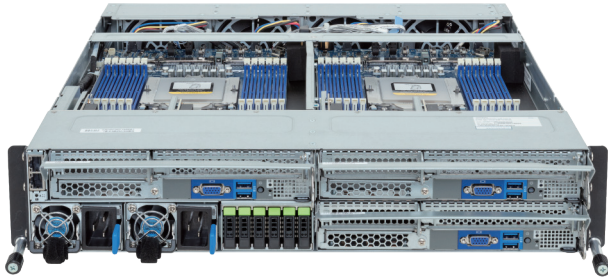


# H223-Z10-AAP1

High Density Server - 2U 3-Node UP 6-Bay E1.S



## Features

- 2U 3-node front access server system
- Single AMD EPYC™ 9005/9004 Series Processors per node
- 12-Channel DDR5 RDIMM, 12 x DIMMs per node
- Dual ROM Architecture
- 2 x CMC ports
- 6 x 9.5mm E1.S Gen4 NVMe hot-swap bays
- 3 x FHHL PCIe Gen5 x16 slots
- 3 x LP PCIe Gen5 x16 slots
- 3 x OCP NIC 3.0 PCIe Gen5 x16 slots
- 2 x 3000W 80 PLUS Titanium redundant power supply

## Application

Edge, Hybrid/Private Cloud Server

## Specification

<b>Dimensions</b>	2U 3-Node - Front access (W447.8 x H87.5 x D500 mm)	<b>Backplane Board</b>	Speed and bandwidth: PCIe Gen4 x4
<b>Motherboard</b>	MZ13-HD0	<b>TPM</b>	1 x TPM headers with SPI interface (per node) - Optional TPM2.0 kit: CTM010
<b>CPU</b>	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Single processor per node, cTDP up to 240W - At ambient 30°C, cTDP up to 300W	<b>Power Supply</b>	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
<b>Socket</b>	3 x LGA 6096 (Socket SP5)	<b>System Management</b>	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
<b>Chipset</b>	System on Chip	<b>OS Support</b>	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
<b>Memory</b>	12-Channel DDR5 RDIMM, 36 x DIMMs [EPYC 9005] Up to 6000 MT/s [EPYC 9004] Up to 4800 MT/s	<b>System Fans</b>	4 x 80x80x38mm (18,300rpm)
<b>LAN</b>	2 x Chassis Management LAN	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Video</b>	Integrated in ASPEED® AST2600 x 3 - 4 x VGA ports	<b>Packaging Content</b>	1 x H223-Z10-AAP1, 3 x CPU heatsinks 1 x L-shape Rail kit Packaging Dimensions: 857 x 670 x 280 mm
<b>Storage</b>	Front hot-swap: 6 x 9.5mm E1.S Gen4 NVMe Optional Internal M.2: 3 x M.2 (2280/22110), PCIe Gen4 x4	<b>Part Numbers</b>	Barebone package: 6NH223Z10DR000ACP1* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - M.2 expansion card - CMTP192: 9CMTP192NR-00* - RMA packaging: 6NH223Z10SR-RMA-A100
<b>SAS</b>	N/A		
<b>RAID</b>	N/A		
<b>Expansion Slots</b>	3 x FHHL PCIe Gen5 x16 slots 3 x LP PCIe Gen5 x16 slots 3 x OCP NIC 3.0 PCIe Gen5 x16 slots		
<b>Front IO</b>	6 x USB 3.2 Gen1 ports (Type-A), 3 x VGA ports, 2 x CMC ports		



Learn more at <https://www.GIGABYTE.com/enterprise>

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